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AUG 26 2003

U.S. UTILITY Patent Application

APPL NUM 10081425	FILING DATE 02/22/2002	CLASS 08	SUBCLASS 127	CAU 282	EXAMINER
APPLICANTS: Pendse Rajendra; S.B.G.					
CONTINUING DATA VERIFIED: THIS APPLN CLAIMS BENEFIT OF 60/272,280 02/27/2001 S.B.G.					
FOREIGN APPLICATIONS VERIFIED: NONE S.B.G.					
PG-PUB DO NOT PUBLISH <input type="checkbox"/>			RESCIND <input type="checkbox"/>		
Foreign priority claimed <input type="checkbox"/>			ATTORNEY DOCKET NO		
35 USC 119 conditions met <input type="checkbox"/>			CPAC 1011-2 US		
Verified and Acknowledged Examiners's initials S.B.G.					
TITLE : Apparatus and process for precise encapsulation of flip chip interconnects					

NOTICE OF ALLOWANCE MAILED

ISSUE FEE

Amount Due

\$ 1600

Date Paid

5/14/03



TERMINAL

DISCLAIMER

Formal Drawings:

DRAWINGS

Sheets Drwg.

Figs. Drwg.

Print Fig.

CLAIMS ALLOWED

Total Claims

Print Claim for O.G.

NOTICE OF ALLOWANCE MAILED

ISSUE FEE

Amount Due

Date Paid

ISSUE BATCH NUMBER

FILED WITH:

☐ DISK (CRF)

☐ CD-ROM

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